



GSW

Gold & Silver Alloy wire

Gold Bonding wire is the primary method of making interconnections between an integrated circuit (IC), a printed circuit board (PCB) and a lead frame during semiconductor device fabrication.

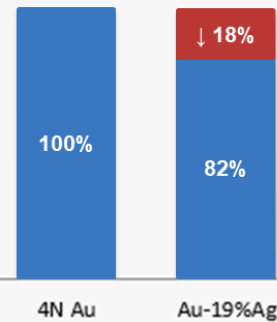
LT Metal has wide range of gold bonding wire for various kind of package types and materials.

TYPE : G3

■ Purpose & Advantages

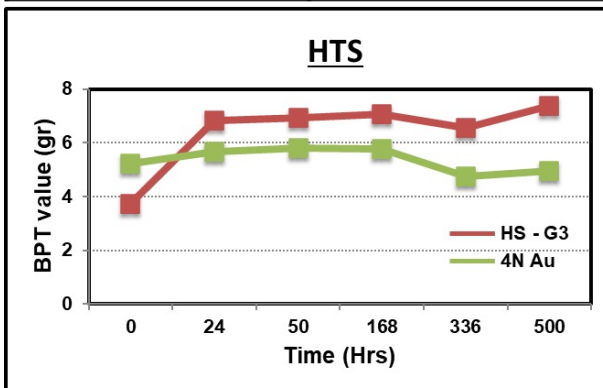
- New cost-saving solution (15~20% lower than gold wire)
- Stable bonding ability in air atmosphere
- Higher strength & stiffness than gold wire
- No need for copper bonder kits & utilities
- Similar bonding performance compared to gold wire (Bondability, Loop control)

Cost Save Effectiveness



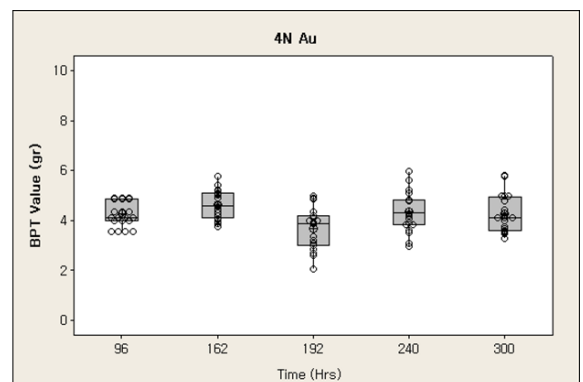
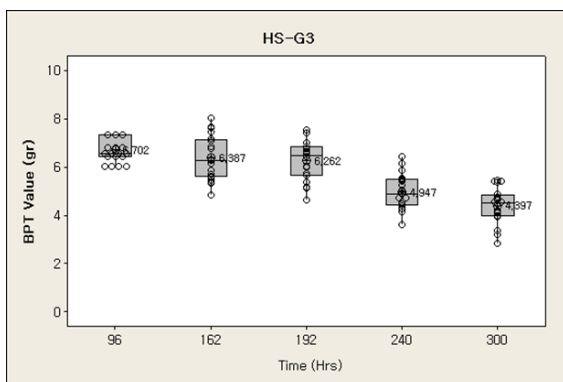
◆ Reliability Performance

Test Condition	
Wire diameter	0.8mil
Temperature	150°C
Chamber condition	Air

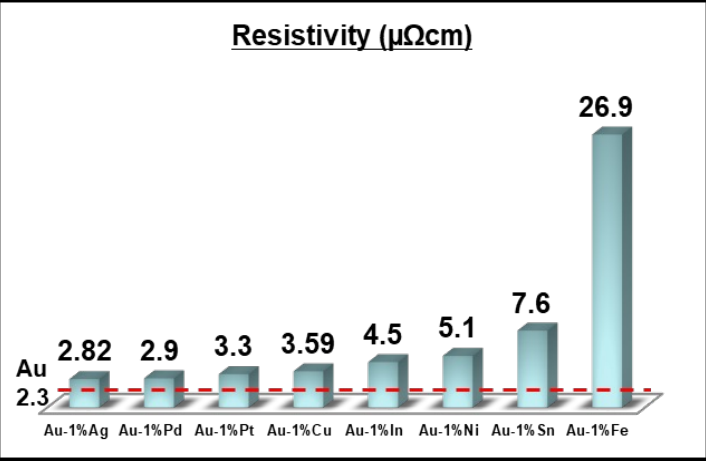


Time (hr)	HS-G3	4N Au
48		
96		
168		
336		
500		

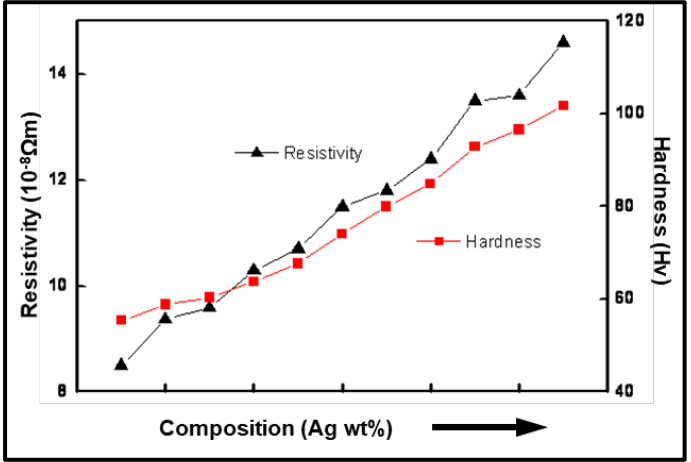
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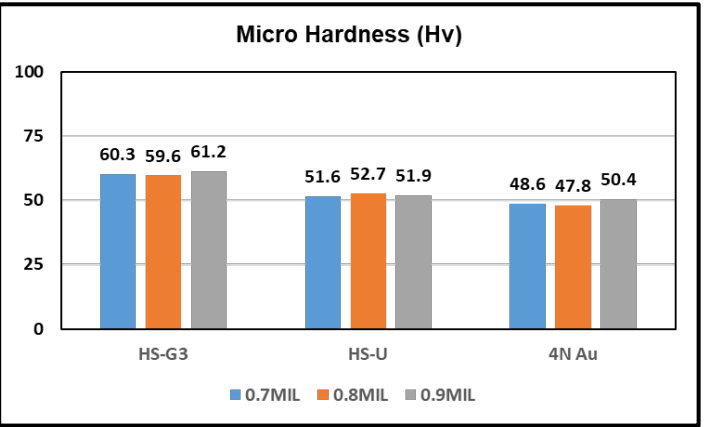
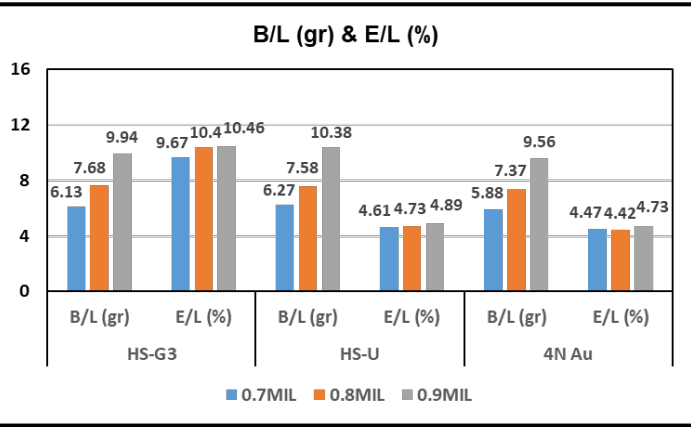
Dopant Effect on the Electrical Resistivity



Composition Change



Mechanical Properties



Resistivity & Fusing Current

